



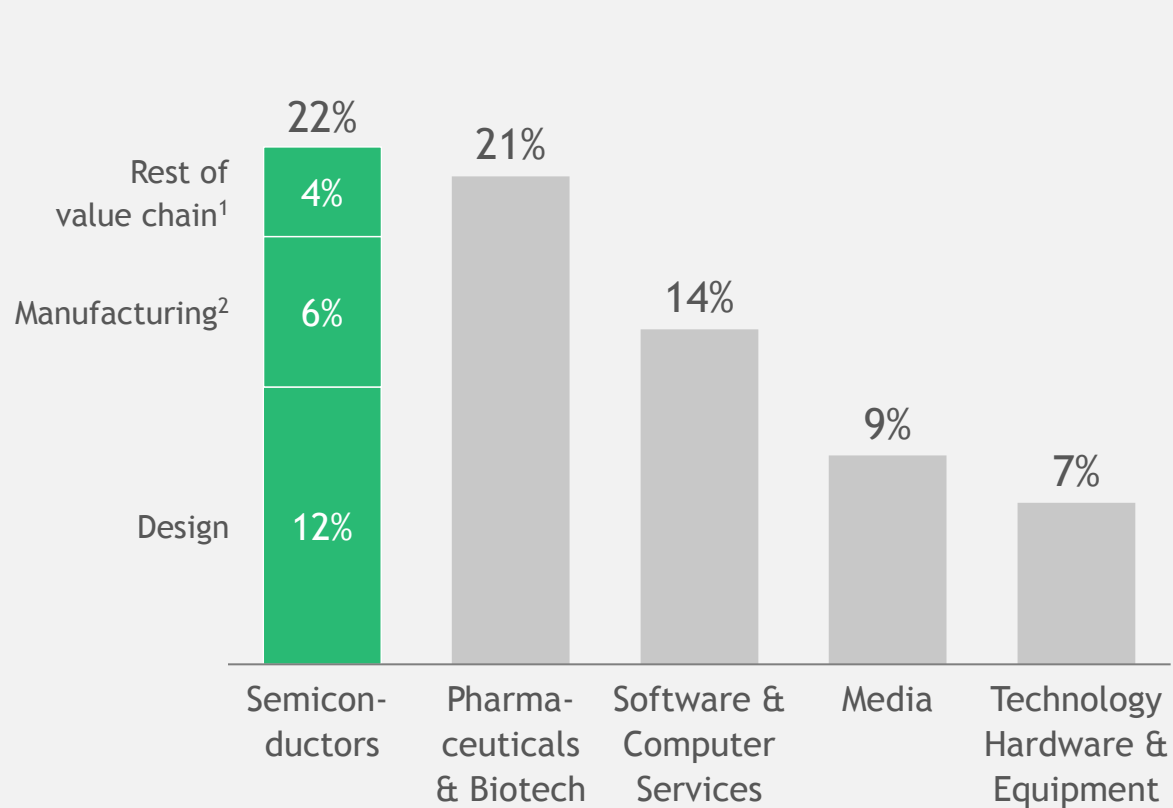
# Strengthening the Global Semiconductor Supply Chain in an Uncertain Era

Slides for webinar

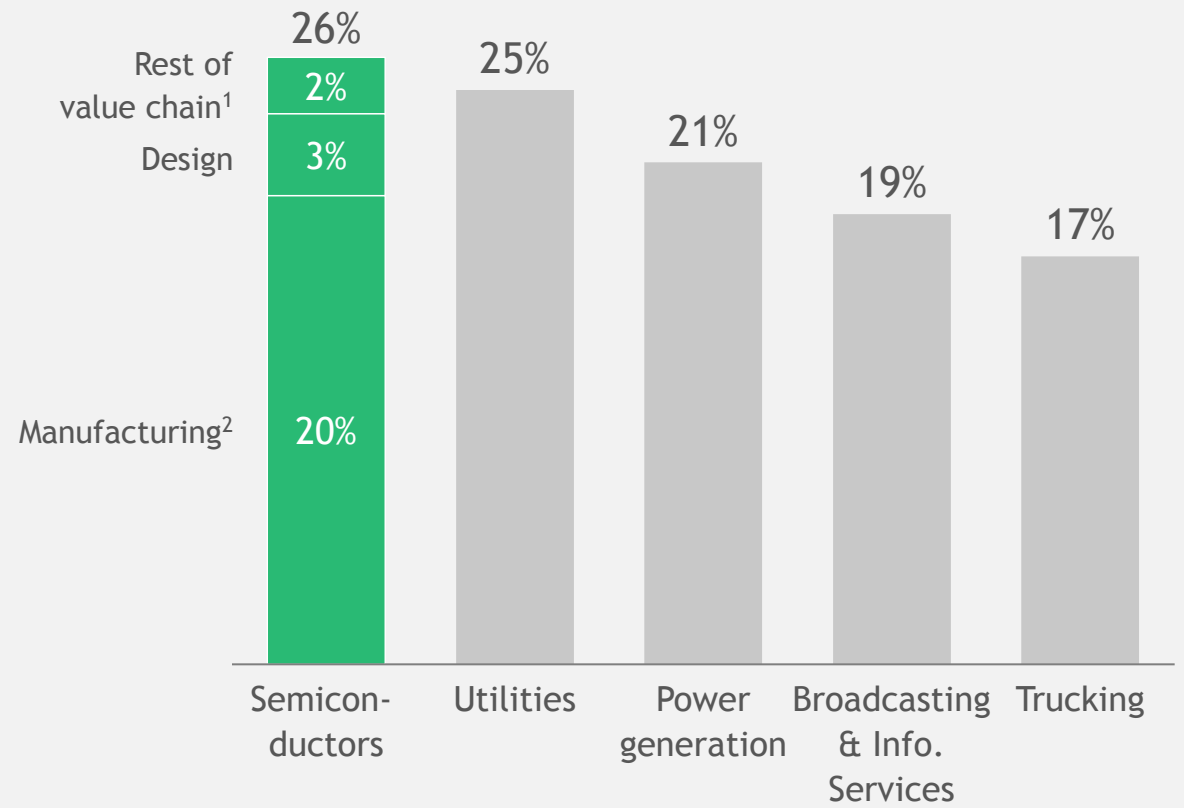
APRIL 6, 2021

# The semiconductor industry ranks high simultaneously in both R&D and capital intensity

R&D AS % OF REVENUES, 2019



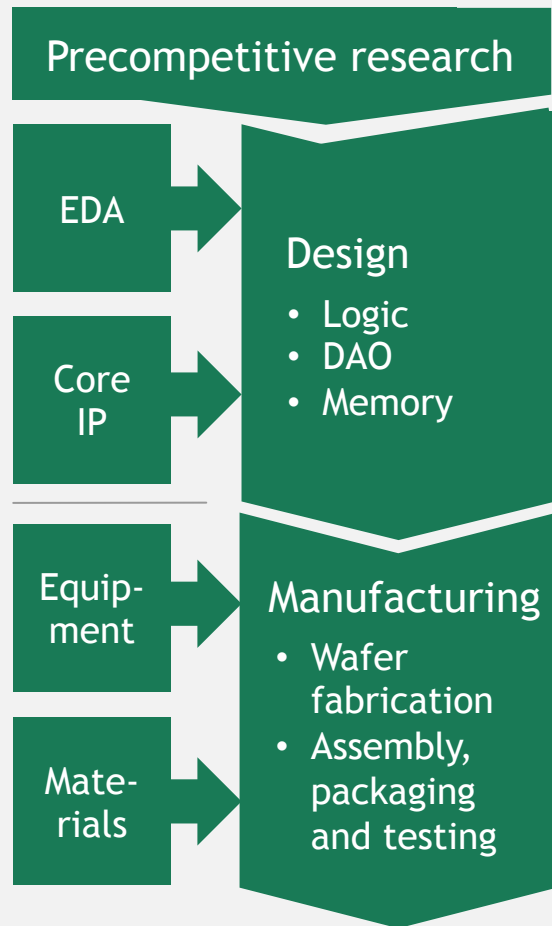
CAPITAL EXPENDITURE AS % OF REVENUES, 2019



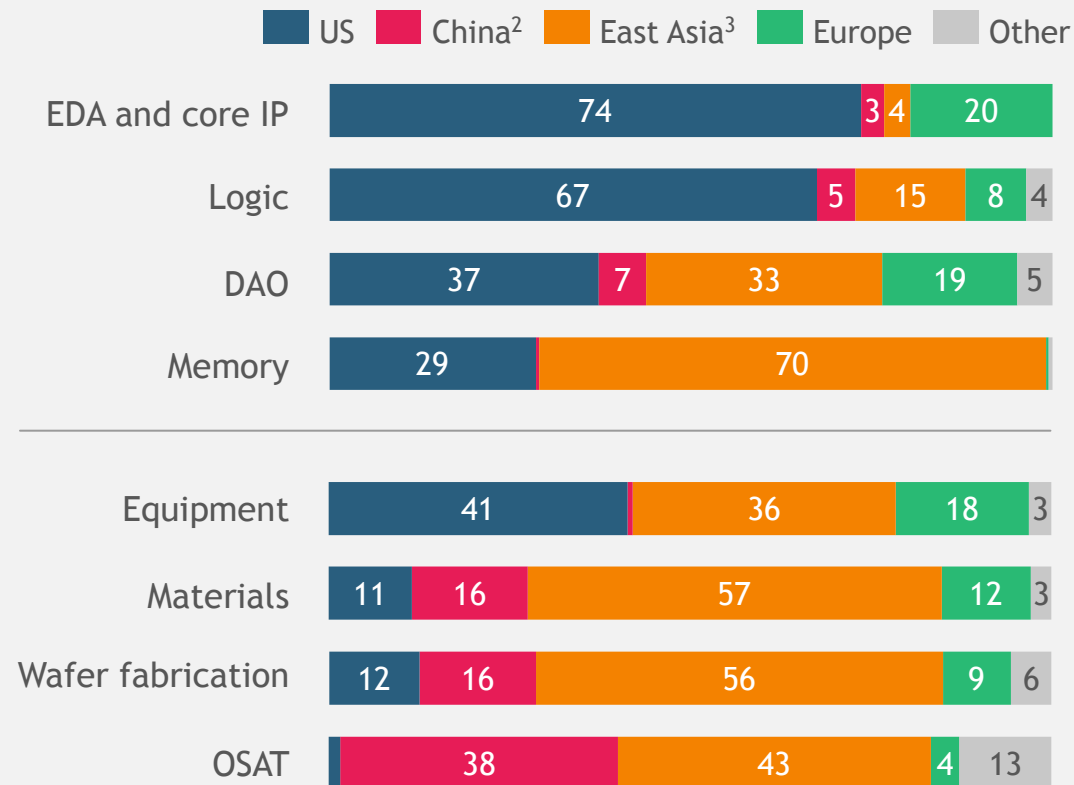
1. Includes EDA and Core IP, Equipment and Materials 2. Includes Wafer Fabrication and Assembly & Test  
Sources: BCG analysis based on Capital IQ data

# The global semiconductor supply chain based on geographic specialization has delivered enormous value for the industry

## SEMICONDUCTOR SUPPLY CHAIN



Share by region<sup>1</sup> (% of worldwide total, 2019)



Costs savings vs. fully localized "self-sufficient" supply chains:

**\$0.9-1.2T**

avoided upfront investment

**\$45-125B**

annual cost efficiencies

**35-65%**






enabled reduction in semiconductor prices

Source: BCG analysis

Note: DAO = discrete, analog, and other (including optoelectronics and sensors); EDA = electronic design automation; OSAT = outsourced assembly and test

1. For EDA and core IP, design, manufacturing equipment and raw materials the regional breakdown is based on company revenues and company headquarters location. For wafer fabrication and OSAT is based on installed capacity and geographic location of the facilities 2. Mainland China 3. East Asia includes South Korea, Japan, and Taiwan

# Five key vulnerabilities identified in the semiconductor supply chain

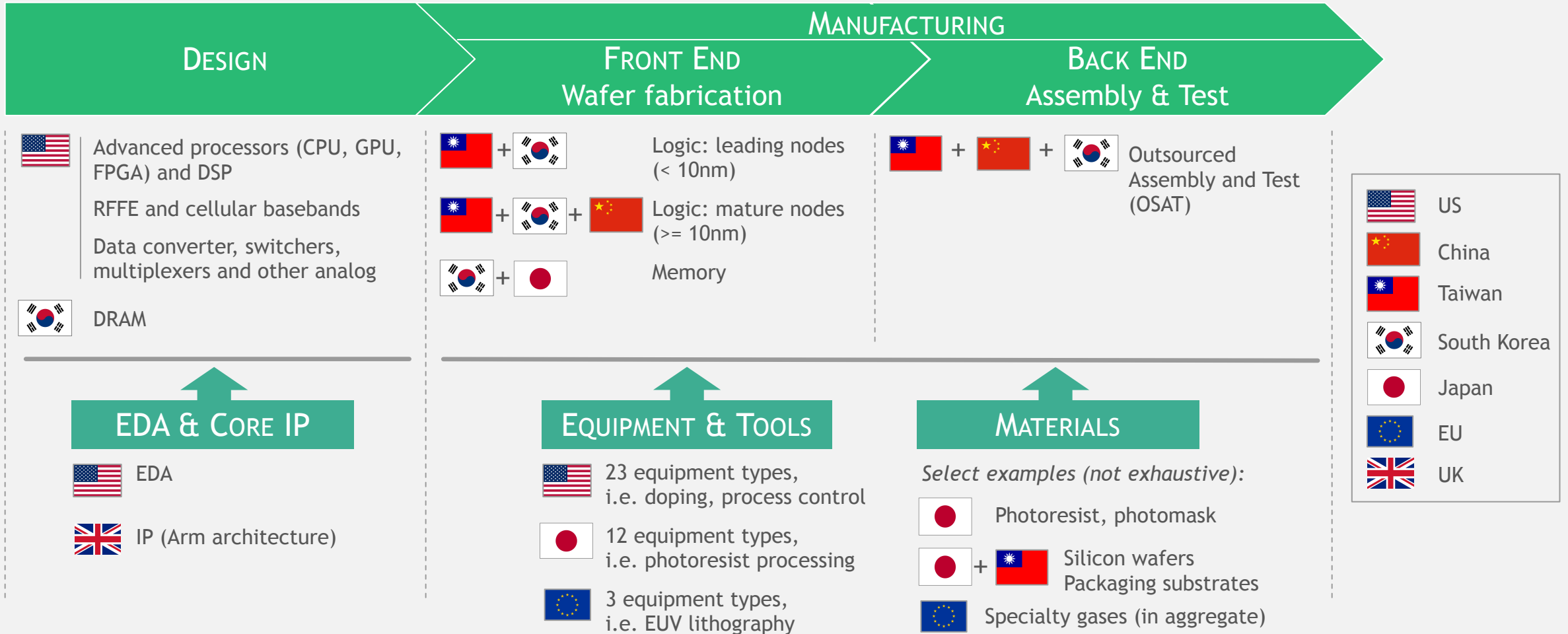
Risk factor		Description	Current examples	
	<p>High geographic concentration of some activities</p>	<p>Single points of failure which may be disrupted by natural disasters, infrastructure failures, cyberattacks or geopolitical frictions</p>	<ul style="list-style-type: none"> <li>• Wafer fabrication</li> <li>• Assembly, packaging &amp; testing</li> <li>• Some specialty materials</li> </ul>	<p>FOCUS AREA IN REPORT</p>
	<p>Geopolitical frictions</p>	<p>Broad export controls over inputs or technologies with no viable alternative suppliers in other countries</p>	<ul style="list-style-type: none"> <li>• US-China frictions</li> <li>• Japan - S. Korea frictions</li> </ul>	
	<p>National self-sufficiency policies</p>	<p>National industrial policies that seek broad import substitution or broadly discriminate against foreign suppliers, leading to distortion in global competition and risk of overcapacity</p>	<ul style="list-style-type: none"> <li>• China policies in pursuit of "self sufficiency" across the semiconductor value chain</li> </ul>	
	<p>Talent constraints</p>	<p>Current growth in talent pool of Science &amp; Engineering graduates is insufficient to meet the industry demand for technical talent</p>	<ul style="list-style-type: none"> <li>• All countries, but US in particular given leadership in R&amp;D intensive activities and reliance on attracting &amp; retaining global talent</li> </ul>	
	<p>Stagnation in funding of basic research</p>	<p>Government programs and funding play a critical role in basic research, which is essential for the semiconductor industry</p>	<ul style="list-style-type: none"> <li>• US government-funded R&amp;D in semiconductors has stagnated and is below overall level across all sectors</li> </ul>	



## GEOGRAPHIC CONCENTRATION

# 50+ points of high geographical concentration across the supply chain (but not all with the same level of associated risk)

VALUE CHAIN ACTIVITIES WHERE ONE SINGLE REGION ACCOUNTS FOR ~65% OR MORE OF GLOBAL SHARE<sup>1</sup>



1. For Design, EDA & Core IP, Equipment & Tools and Raw Materials: global share measured as % of revenues, based on company headquarter location. For Manufacturing (both Front End and Back End) measured as % of installed capacity, based on location of the facility

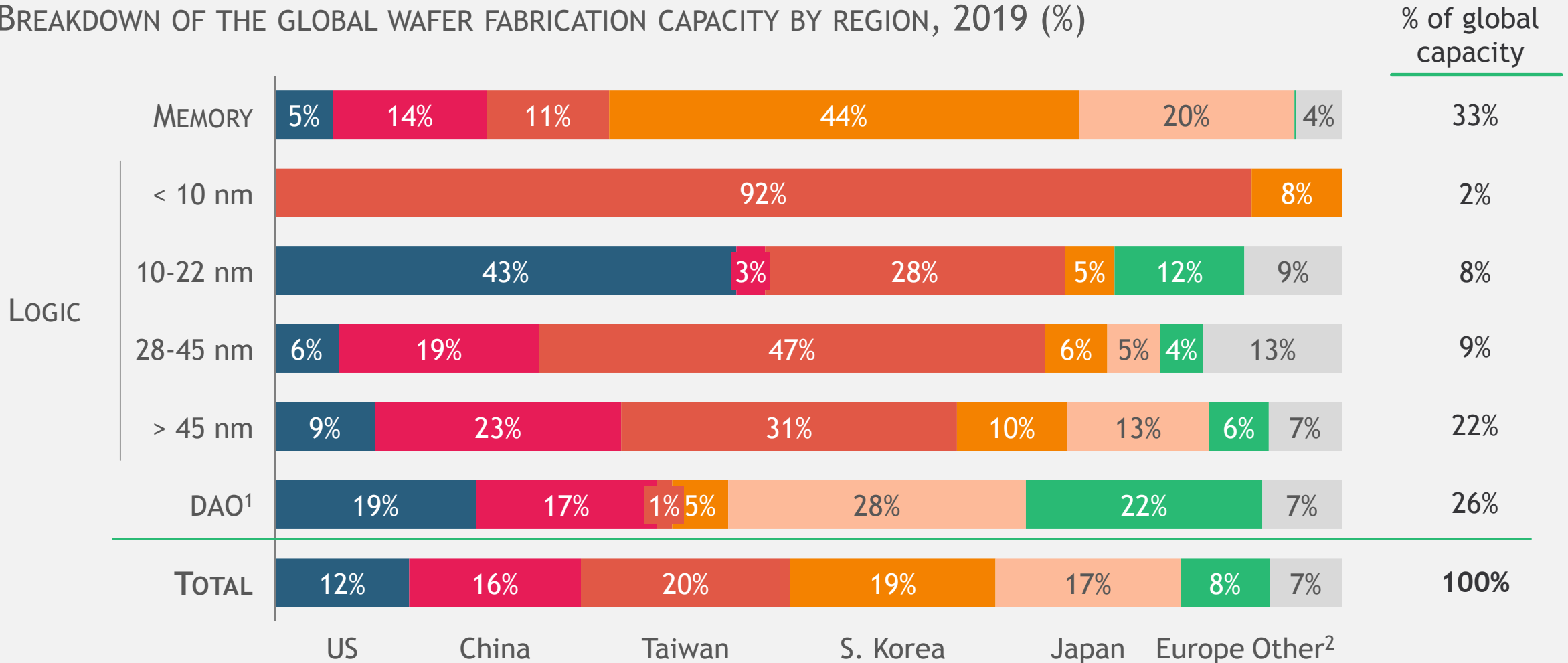
Sources: BCG analysis with data from Gartner, SEMI, UBS; SPEEDA



## GEOGRAPHIC CONCENTRATION

East Asia + China concentrate ~75% of the wafer fabrication capacity; in particular, ~90% of advanced logic capacity <10 nm is located in Taiwan

BREAKDOWN OF THE GLOBAL WAFER FABRICATION CAPACITY BY REGION, 2019 (%)



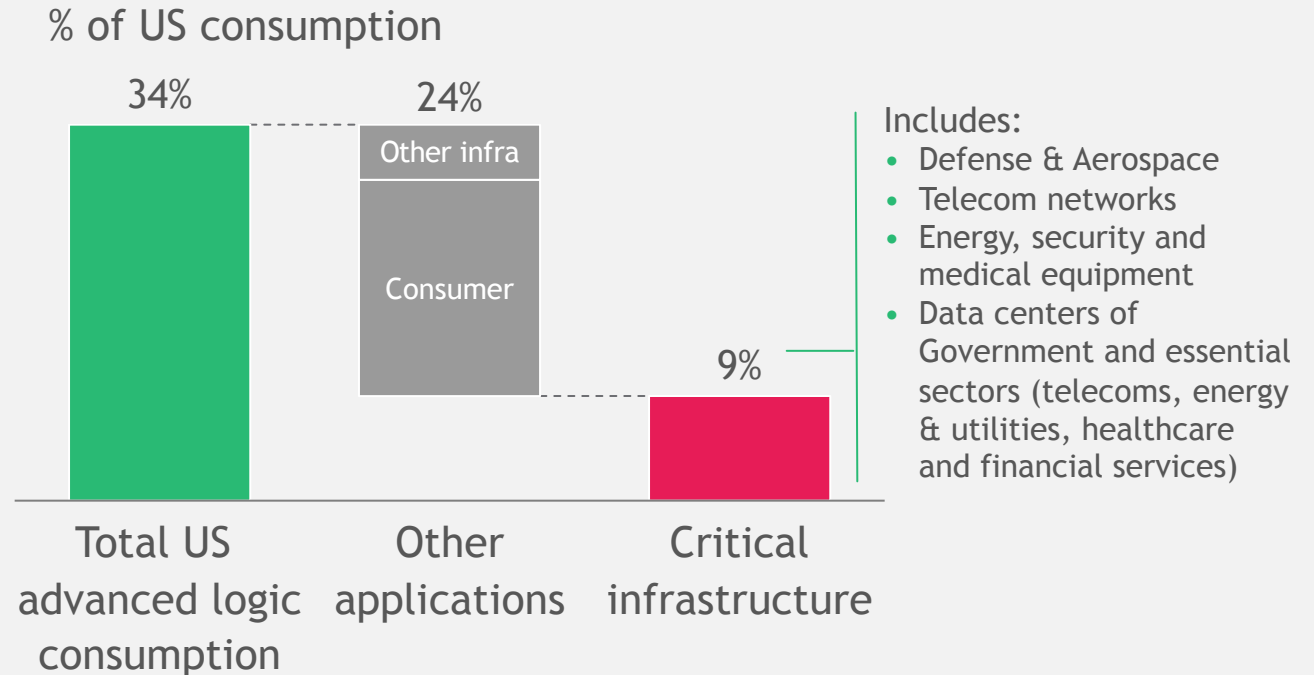
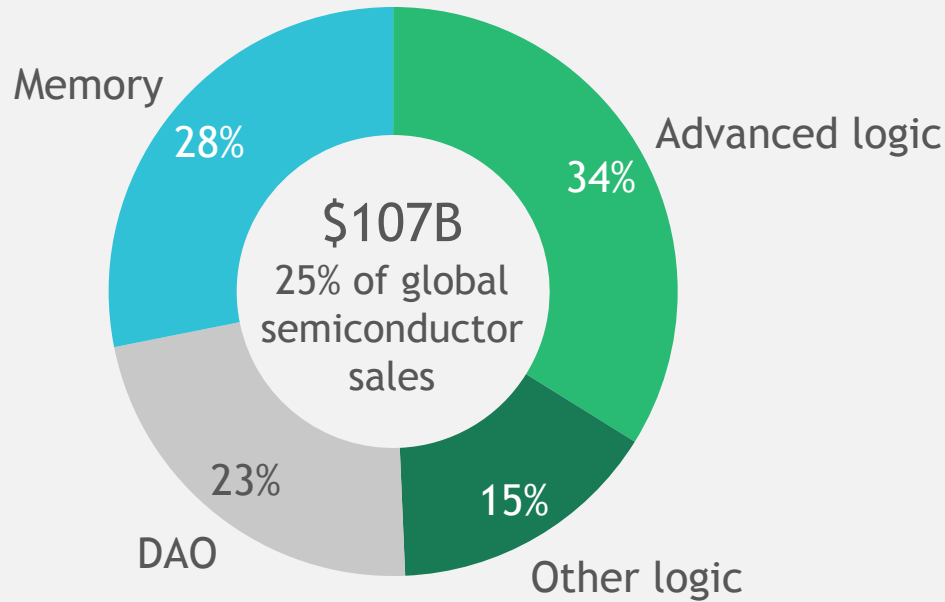
1. Discrete, analog and optoelectronics and sensors 2. Other includes Israel, Singapore and the rest of the world  
Sources: BCG analysis with data from SEMI fab database



## GEOGRAPHIC CONCENTRATION

# Enhancing the supply chain resilience through a focused approach: example of US minimum viable capacity for advanced logic (< 10nm)

## BREAKDOWN OF TOTAL US SEMICONDUCTOR CONSUMPTION, 2019



% US Capacity / Consumption

49%

10-year investment<sup>2</sup> in new fabs for onshore coverage in 2030 (\$B) (Private sector + Government incentives<sup>3</sup>)

980+420  
60-65 new fabs

0%<sup>1</sup>

140+60  
6-7 new fabs

0%<sup>1</sup>

45+18  
2-3 new fabs of 20-35 kwpm

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